

Figure 1. Example of Wire Bonding Used to Form the Electrical Connections to the Semiconductor Die

Semiconductor Die with Solderable Metal System Allowing Direct Surface Mounting to Printed Circuit Boards

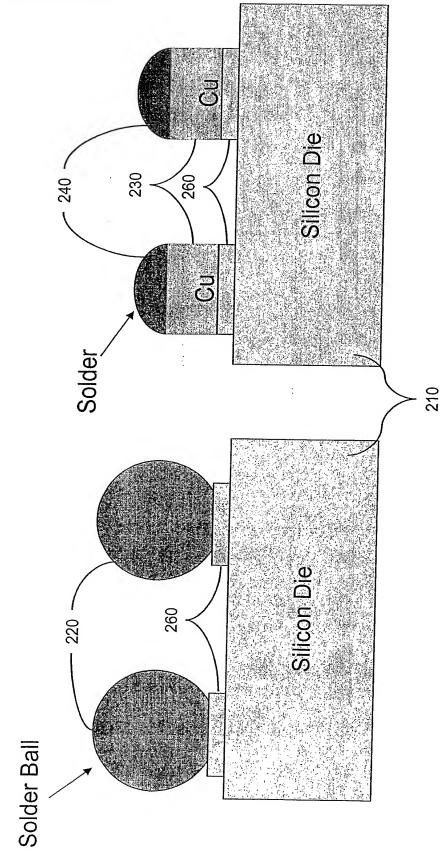


Figure 2. Typical Flip Chip Wafer Bumping Packages

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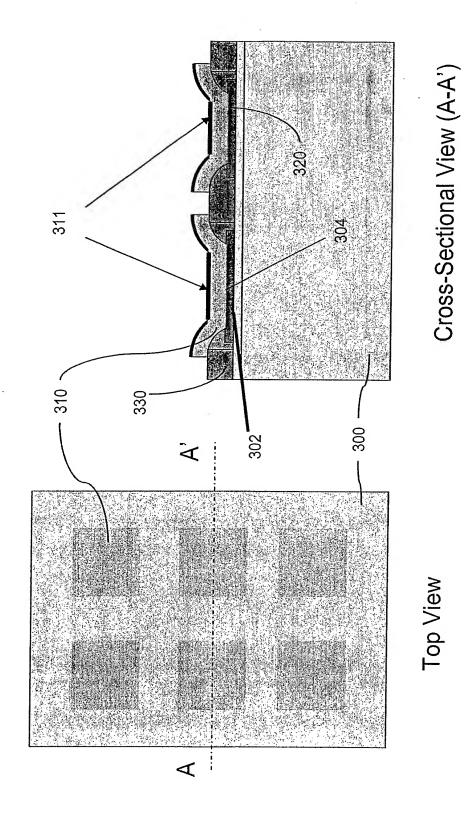
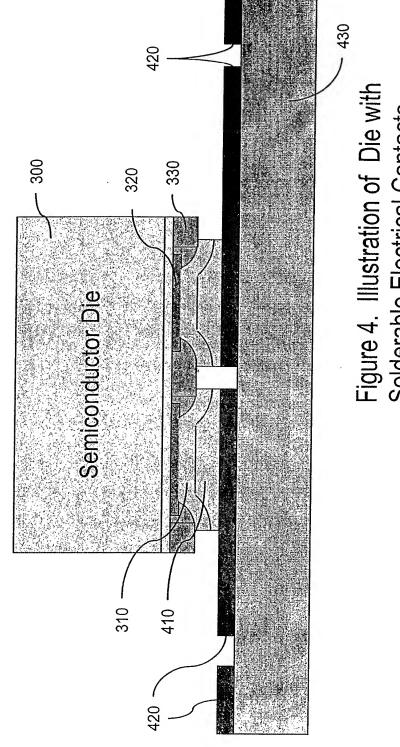


Figure 3. Die with Solderable Metal Contacts for Direct Printed Circuit Board Mounting

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Mounted on Printed Circuit Board Solderable Electrical Contacts